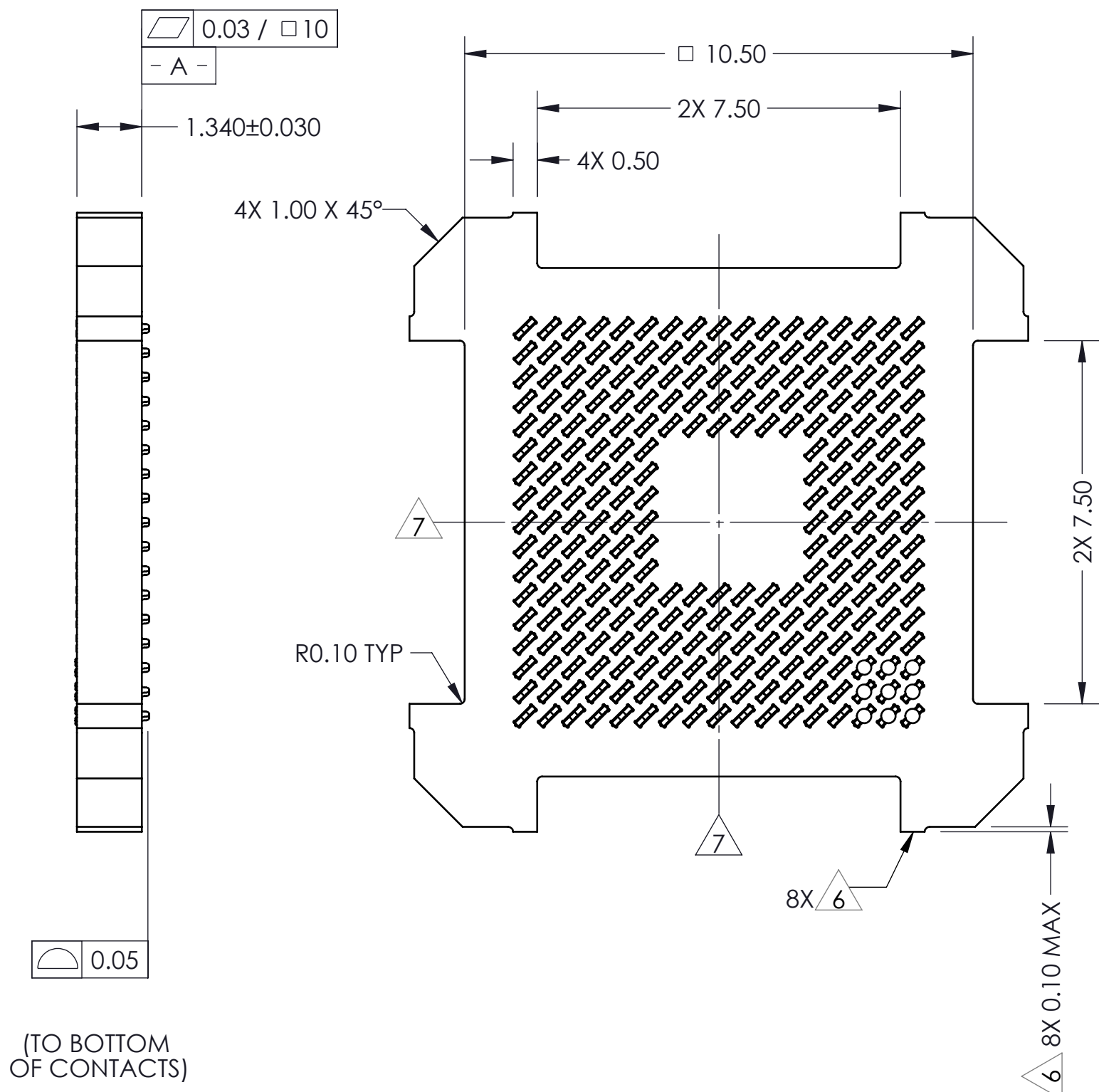
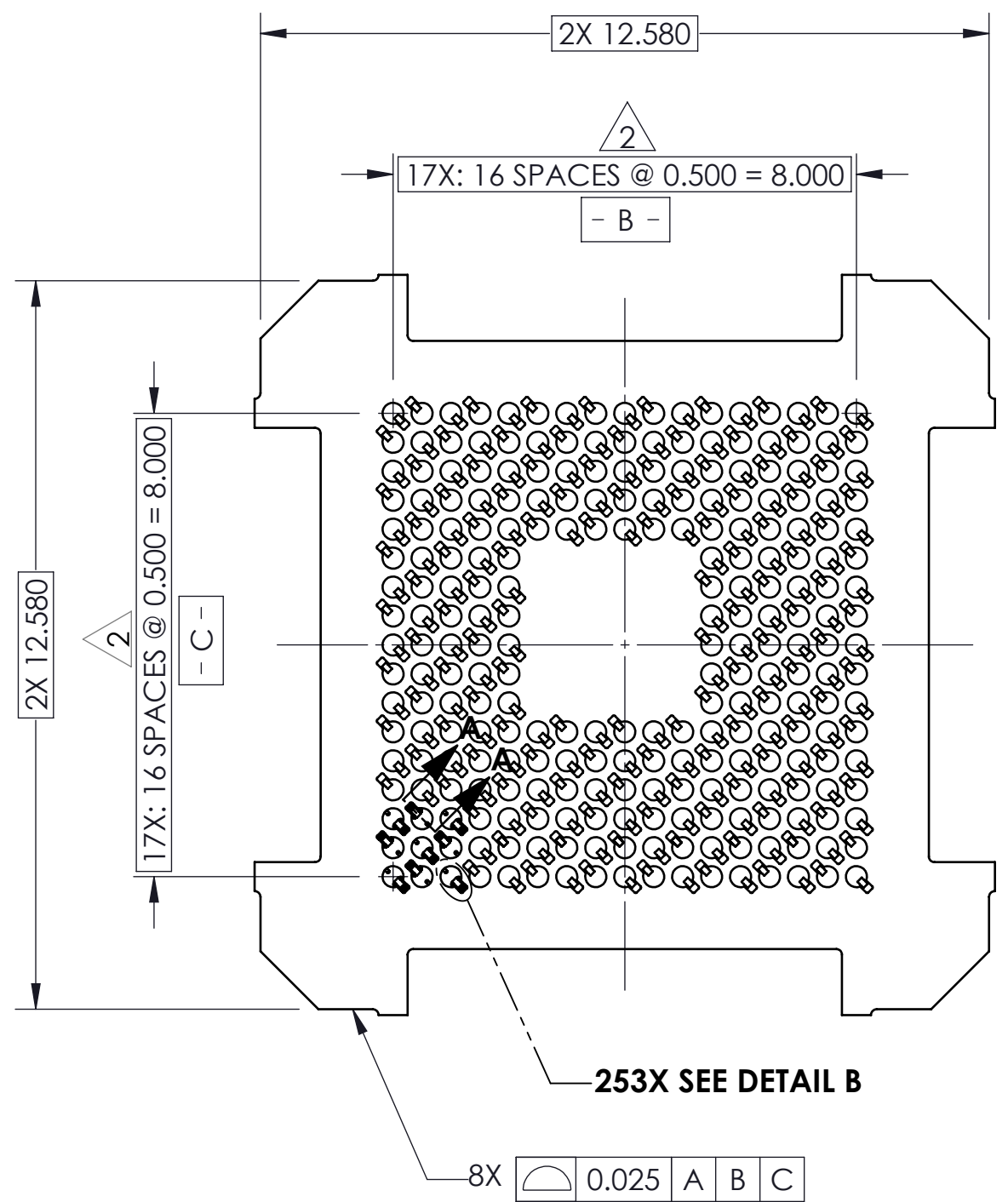
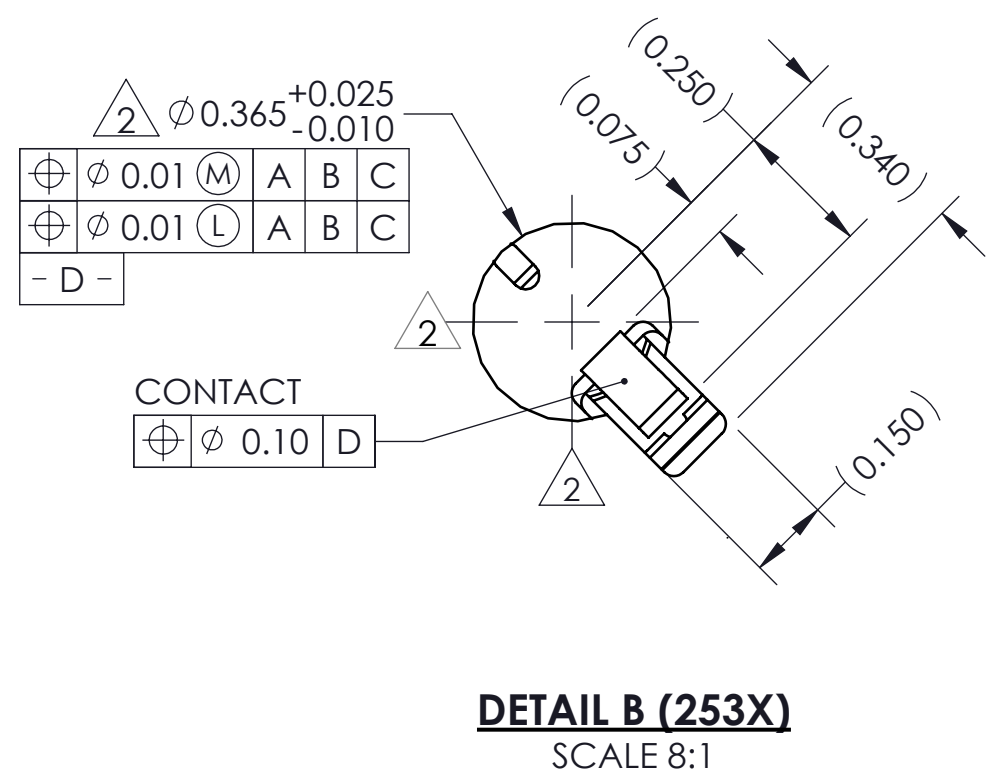
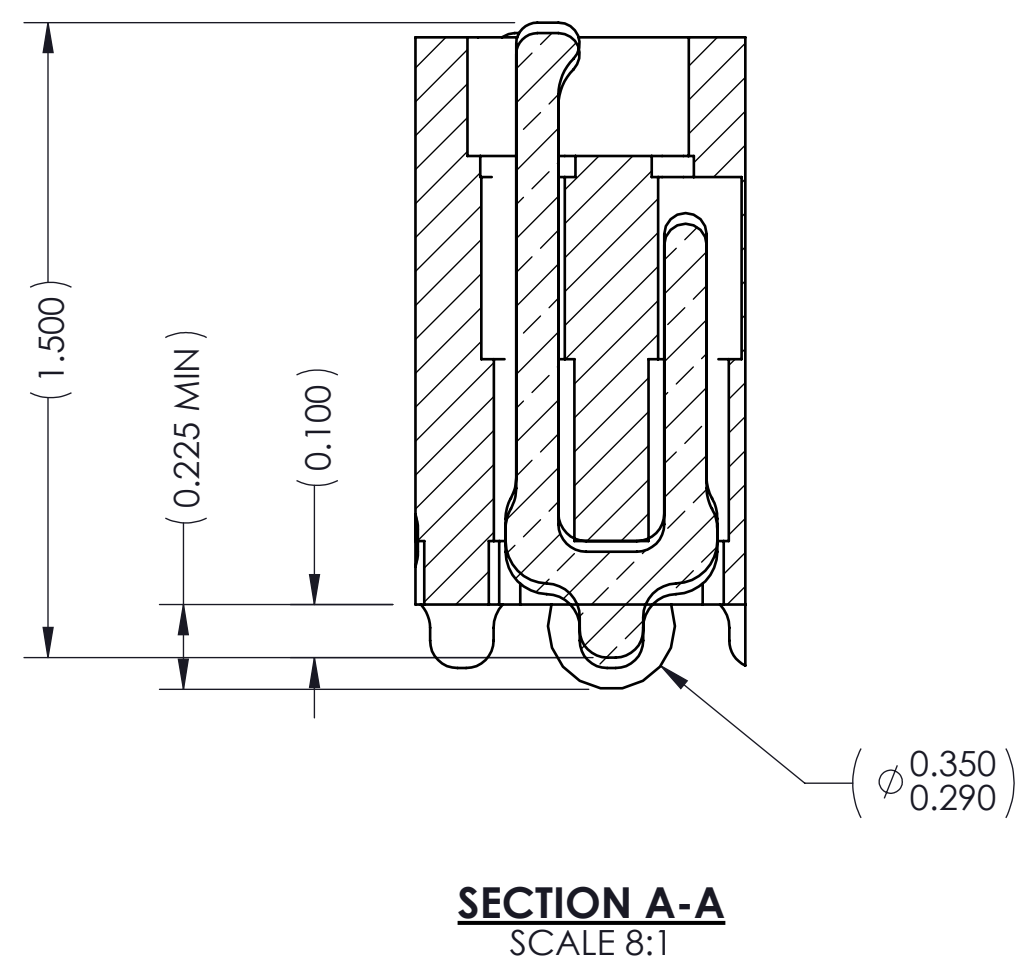


REV	ECO	BY	DESCRIPTION	APV	DATE
A	31797	PAR	INITIAL DESIGN	NSJ	06/17/16



Part Number	Description
108387-0078	SCKT, 253G4012.5-0.50, EUT EUTECTIC SOLDER BALLS
103864-0144	PRESS, DEVICE INSERT, GRYP 12.5X12.5 (SOLD SEPARATELY)
105900-0004	EXTRACTION TOOL, 4 X 53 (SOLD SEPARATELY)
104553-0243	STENCIL, FLEX, 253G4012.5-0.50 (SOLD SEPARATELY)
106083-0057	FRAME, ALIGN, G40, 12.5X12.5 (SOLD SEPARATELY)

(TO BOTTOM OF CONTACTS)



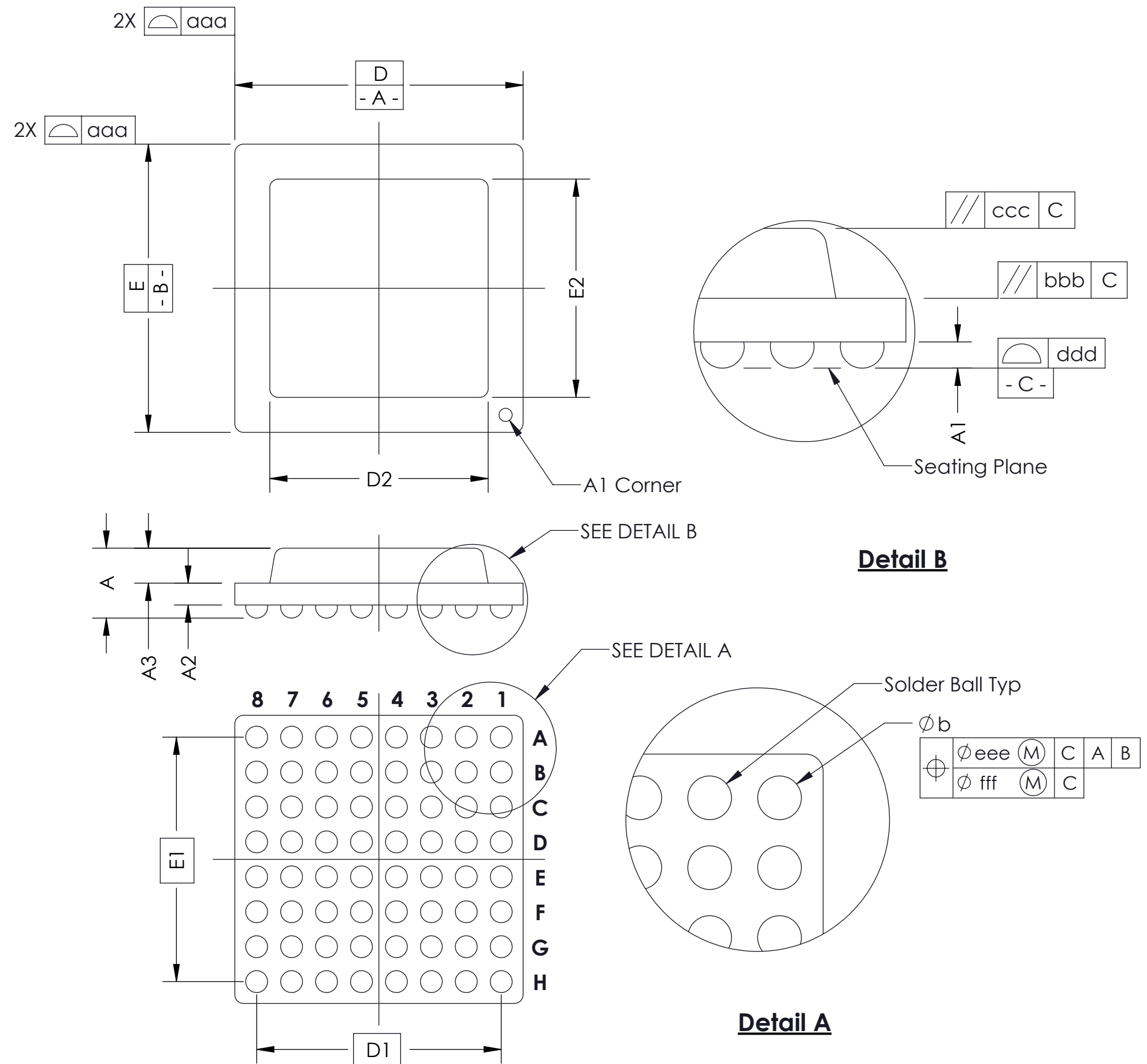
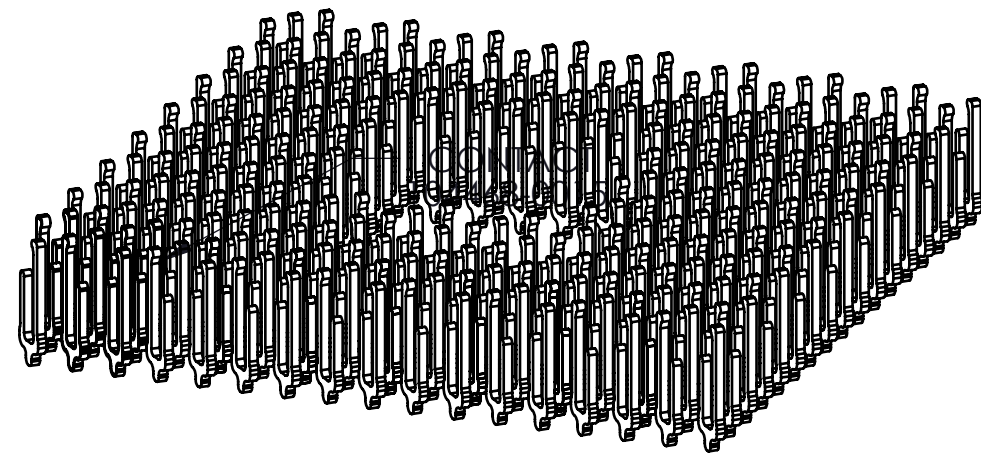
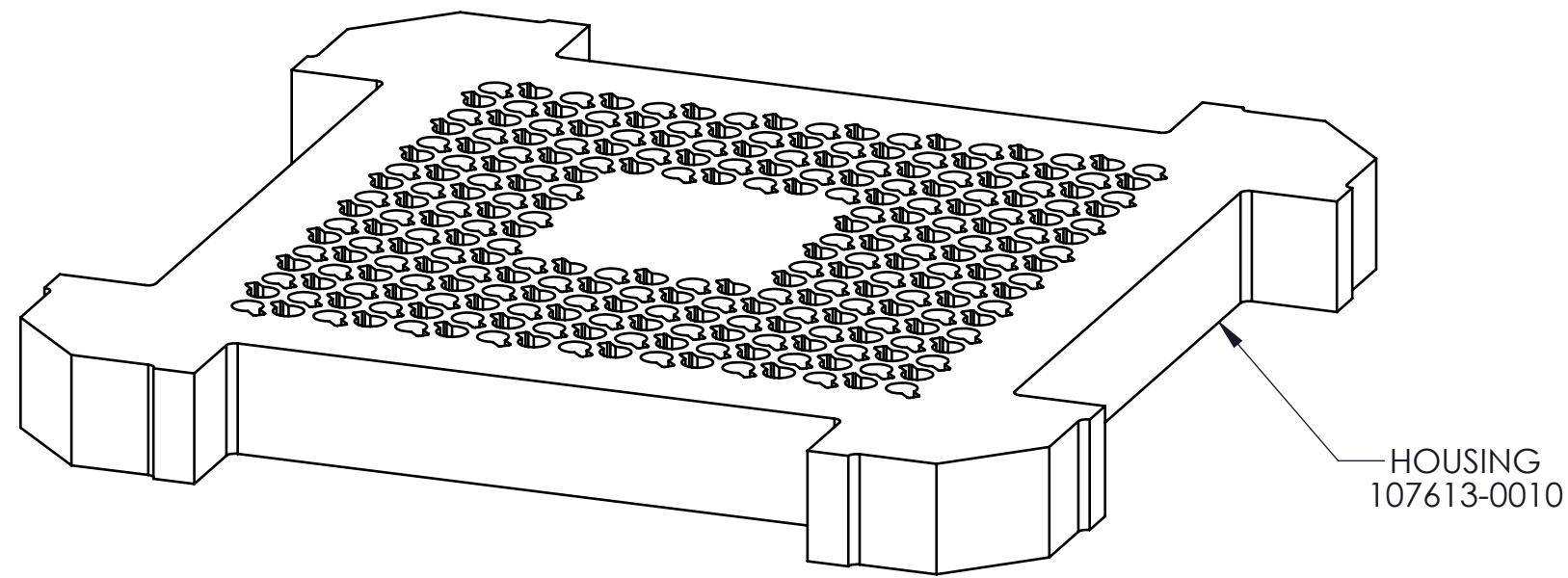
NOTES:

- REFERENCE HSI0 TECHNOLOGIES PART NUMBER 103862-0001 FOR SOLDER ATTACHMENT.
- LOCATES CENTER OF CONTACT/ SLOT.
- REFERENCE HSI0 TECHNOLOGIES PART NUMBER 103863-0001 FOR APPLICATION NOTES.
- FOOTPRINT PART NUMBER IS 104311-0398.
- DATUMS - B - AND - C - ARE DETERMINED BY Ø0.365 OPENINGS ON CORNER SLOTS.
- TOOLING MARKS PERMITTED. MAXIMUM 0.10 PROTRUSION (SHOWN).
- CENTER OF CONTACT PATTERN.
- ALL CONTACTS/ SOLDER BALLS ARE NOT SHOWN TO MINIMIZE FILE SIZE.

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	INTERPRET GEOMETRIC TOLERANCING PER:	CHECKED NSJ	DATE 06/17/16		DWG. NO. 108387-0078
	MATERIAL SEE BOM	LEGEND: △ NOTE CALLOUT ○ REVISION CHANGE ○ ITEM NUMBER			REV A
	FINISH	DO NOT SCALE DRAWING			SCALE: 10:1 SIZE: C SHEET 1 OF 2

SOCKET FOR DEVICES THAT ARE WITHIN THESE SPECIFICATIONS					
Lead Count	N	253	Package Size	D	12.50
Columns	ND	17		E	12.50
Rows	NE	17	Ball Spacing	D1	8.000
Pitch	e	0.500		E1	8.000
Ball Size	b	0.30±0.05	Encapsulant/ Top Size	D2	N/A
Total Thickness	A	N/A		E2	N/A
Ball Height	A1	0.225 MIN	Pattern Style	Irregular*	
Substrate Thickness	A2	N/A	Perimeter Rows	N/A	
Top Thickness	A3		Center Array	N/A	
Form Tolerances					
Edge	aaa	0.10	Bottom	ddd	0.08
Substrate	bbb	0.10	Position	eee	0.10
top	ccc	0.10	Position	fff	0.05

ALL DIMENSIONS ARE IN MILLIMETERS.
* SEE FOOTPRINT FOR PATTERN DETAILS.



Generic Representation with Full Grid Array

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UNLESS OTHERWISE SPECIFIED:	NAME	DATE	HSIO TECHNOLOGIES, LLC. 13400 68th AVENUE NORTH MAPLE GROVE, MINNESOTA 55311 763-447-6260
DIMENSIONS ARE IN MILLIMETERS	DRAWN	PAR	
TOLERANCES:	CHECKED	NSJ	
ANGULAR: ± 1° X.X ±0.25 X.XX ±0.10 X.XXX ±0.050			TITLE: SCKT, 253G40 12.5-0.50 EUTECTIC SOLDER BALLS
LEGEND: △ NOTE CALLOUT ◻ REVISION CHANGE ○ ITEM NUMBER	DWG. NO. 108387-0078		REV A
SCALE: 10:1		SIZE: C	SHEET 2 OF 2